



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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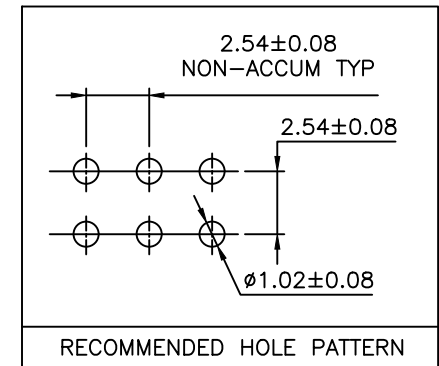
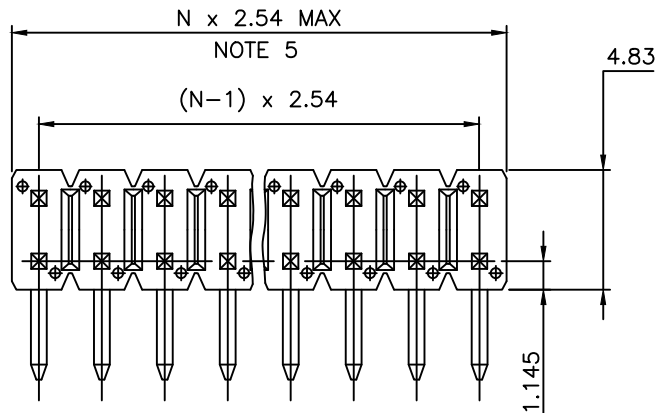
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT NUMBER

77317-YXX-XXLF

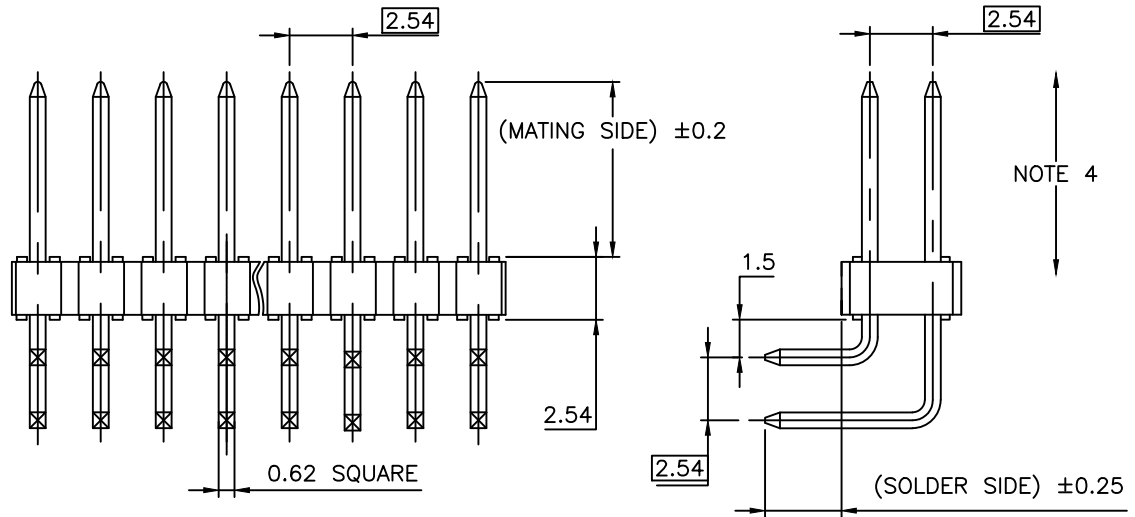
- RoHS COMPATIBLE
SEE NOTE 7
- TOTAL NB OF POSITIONS 04 TO 72
- PIN STYLE SEE SHEET 2
- PLATING SEE SHEET 2



NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. STANDARD PACKAGING IN POLYBAG
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS $N \times 2.54 = 20.32\text{mm}$
6. UNDERPLATING : $1.27\mu\text{m}$ Ni MIN
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, $2\mu\text{m}$ MINIMUM MATTE TIN OVER $1.27\mu\text{m}$ MINIMUM NICKEL UNDERPLATE.
- b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO $260^\circ\text{C} \pm 5^\circ\text{C}$ SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code SEE NOTES		surface ISO 1302 <input checked="" type="checkbox"/> ISO 406 ISO 1101		tolerance ISO 406 ISO 1101		projection 		product family BERGSTIK	
ltr ecn no dr date		tolerances unless otherwise specified		.X ± 0.3		mm		title UNSHR.HEADER RA DR TMT	
AH B-18916 LMU 14.09.29		angles linear		.XX ± 0.15		scale 5:1		dwg no sheet 1 of 2 size	
AJ B-19783 AMA 14.12.18				.XXX ± 0.05				77317 A3	
AK B-21242 AMA 15.06.25								type CUSTOMER Drawing	
AL F-23305 AMA 16.02.19		dr D.LE		01.01.24					
AM F-27765 DDE 17.08.21		engr JM.C		01.01.24					
AN F-29937 DDE 18.04.20		chr JM.C		01.01.24					
		appd JF.N		01.01.24					
sheet index	revision sheet	AN 1	AK 2						

PLATING

- 1 = 0.76µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL
- 4 = 2µm TIN MIN FULL PLATED
- 5 = 0.25µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL
- 8 = 0.38µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL
- G = 0.76µm FULL GXT
- S = 0.38µm FULL GXT
- 1.27µm NICKEL MIN UNDERLAYER FOR ALL PLATING VERSIONS

PRODUCTS SPECIFICATIONS		
PIN STYLE	MATING	SOLDER
01	5.72	2.57
03	5.84	2.41
04	5.84	3.05
10	8.07	3.05
12	6.80	3.05
14	10.00	2.70
15	7.00	16.40
16	7.80	13.50
17	7.48	1.60
18	8.80	2.90
19	2.60	2.60
20	N/A	
21	10.89	3.05
22	3.51	3.51
23	7.20	3.05



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mat'l. code		surface		tolerance		projection		product family		
SEE NOTES		ISO 1302 ✓		ISO 406 ISO 1101				BERGSTIK		
ltr	ecn no	dr	date	tolerances unless otherwise specified				title		
AG	B-21242	AMA	15.06.25	angles	linear	mm		UNSHR.HEADER		
AH	F-23305	AMA	16.02.19			scale 5:1		RA DR TMT		
AJ	F-27765	DDE	17.08.21					dwg no		
AK	F-29937	DDE	18.04.20	dr	D.LE	01.01.24		sheet 2 of		size
				engr	JM.C	01.01.24		77317		A3
AE	F11-0320	LMU	12.01.25	chr	JM.C	01.01.24		type		
AF	B-18916	LMU	14.09.29	appd	JF.N	01.01.24		CUSTOMER Drawing		
sheet	revision									
index	sheet									